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|  | Docket Number (Optional) | | Application Number |
| | 01300033AA | | 09/198,376 |
| | Applicant(s) | | |
| A. Okamoto | | Group Art Unit | |
| Filing Date | | 3743 | |
| 09/198,376 | | | |

U.S. PATENT DOCUMENTS

| EXAMINER INITIAL | REF | DOCUMENT NUMBER | DATE | NAME | CLASS | SUBCLASS | FILING DATE IF APPROPRIATE |
|---------------------|-----|-----------------|---------|------------------|-------|----------|-------------------------------|
| AF | 1 | 5,330,708 | 7-19-94 | Martinson et al. | | | 4-26-93 |
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FOREIGN PATENT DOCUMENTS

| | REF | DOCUMENT NUMBER | DATE | COUNTRY | CLASS | SUBCLASS | Translation | |
|--|-----|-----------------|------|---------|-------|----------|-------------|----|
| | | | | | | | YES | NO |
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OTHER DOCUMENTS (Including Author, Title, Date, Pertinent Pages, Etc.)

| | | |
|----|---|--|
| AF | 1 | European Office Action dated 8-18-03 |
| AF | 2 | Article titled "Understanding doped V/sub 2/0/sub 3/ as a functional positive temperature coefficient material" Authors: Hendrix, Chen, Wang and Cui dated 6-92 |

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| EXAMINER | /Allen Flanigan/ | DATE CONSIDERED | 06/29/2006 |
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EXAMINER: Initial if citation considered, whether or not citation is in conformance with MPEP Section 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.